In the Claims:

Claims 1-13 (canceled).

Claim 14 (original): A method for fabricating a composite capacitor in a semiconductor die, said method comprising steps of:

depositing a lower interconnect metal layer;

forming an upper electrode of a lower capacitor over said lower interconnect metal layer;

patterning said lower interconnect metal layer to form a lower electrode of said lower capacitor;

depositing an upper interconnect metal layer;

forming an upper electrode of an upper capacitor over said upper interconnect metal layer;

patterning said upper interconnect metal layer to form a lower electrode of said upper capacitor.

Claim 15 (original): The method of claim 14 further comprising a step of connecting said upper electrode of said lower capacitor to said lower electrode of said upper capacitor by at least one via.

Claim 16 (original): The method of claim 14 further comprising a step of connecting said lower electrode of said lower capacitor to said upper electrode of said upper capacitor by at least one via.

Claim 17 (original): The method of claim 14 further comprising a step of forming a high-k dielectric between said lower and upper electrodes of said lower capacitor.

Claim 18 (original): The method of claim 17 wherein said high-k dielectric is selected from the group consisting of silicon oxide, silicon nitride, tantalum pentoxide, aluminum oxide, hafnium oxide, zirconium oxide, zirconium aluminum silicate, hafnium silicate, and hafnium aluminum silicate.

Claim 19 (original): The method of claim 14 further comprising a step of forming a high-k dielectric between said lower and upper electrodes of said upper capacitor.

Claim 20 (original): The method of claim 19 wherein said high-k dielectric is selected from the group consisting of silicon oxide, silicon nitride, tantalum pentoxide, aluminum oxide, hafnium oxide, zirconium oxide, zirconium aluminum silicate, hafnium silicate, and hafnium aluminum silicate.

Claim 21 (original): The method of claim 14 wherein said upper electrode of said lower capacitor and said upper electrode of said upper capacitor comprise metal selected from the group consisting of titanium nitride and tantalum nitride.

Claim 22 (original): The method of claim 14 wherein said upper electrode of said lower capacitor and said upper electrode of said upper capacitor are fabricated utilizing a common mask.

Respectfully Submitted, FARJAMI & FARJAMI LLP

Michael Farjami, Esq. Reg. No. 38,135

Date: <u>6/23/05</u>

FARJAMI & FARJAMI LLP 26522 La Alameda Ave., Suite 360 Mission Viejo, California 92691 Telephone: (949) 282-1000

Facsimile: (949) 282-1002

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being filed by facsimile transmission to United States Patent and Trademark Office at facsimile number 703-872-9306 on the date stated below. The facsimile transmission report indicated that the facsimile transmission was successful.

Christina	Carter
Name of Person Performing	Facsimile Transmission
Phristina	Carta 6/23/05
Signature	Date
-	•
	•
CERTIFICATE OF MAILIN	
	rrespondence is being deposited al Service as first class mail in a
envelope addressed: Comm	nissioner for Patents,
P.O. Box 1450, Alexandria.	, VA 22313-1450
Date of Deposit:	
,	
	•
Name of Person Mailing Pa	per and/or Fee
. •	•
Signature	Date ,

Page 5 of 5